

REMARKS

This is a full and timely response to the Office Action mailed July 09, 2008, submitted concurrently with a two month extension of time to extend the due date for response to December 09, 2008.

By this Amendment, claims 1, 2, 4-7, 10, 12, 13, 15 and 16 have been amended to more particularly define the present invention and to put the claims in better form under U.S. practice. Further, claims 3, 8, 9, 11 and 14 have been canceled without prejudice or disclaimer to their underlying subject matter. Thus, claims 1, 2, 4-7, 10, 12, 13, 15 and 16 are currently pending in this application. Support for the claim amendments can be readily found variously throughout the specification and the original claims.

In view of these amendments, Applicant believes that all pending claims are in condition for allowance. Reexamination and reconsideration in light of the above amendments and the following remarks is respectfully requested.

Information Disclosure Statement

From Applicant's review of the PTO/SB/08 form enclosed with the Office Action, the Examiner has not indicated her consideration of the foreign patent documents submitted with the Information Disclosure Statement filed June 14, 2006. The Examiner has based her action on the position that documents were not provided for these references. However, Applicant wishes to note that the foreign patent references were submitted to the USPTO on June 14, 2006 as verified by a stamped return postcard from the USPTO (see below). It appears from the electronic file record that the filed foreign patent references were lost or not scanned by the USPTO. Hence, to replace the missing filed foreign patent references, Applicant has resubmitted an Information Disclosure Statement and PTO/SB/08 form citing these references. Applicant has also provided notations in the PTO/SB/08 form for each Japanese patent regarding their respective English language abstracts. Applicant respectfully requests the Examiner to indicate her consideration of the foreign patent documents submitted with the Information Disclosure Statement filed June 14, 2006. Applicant sincerely appreciates the Examiner's consideration in this regard.

Inventor:	Koichi SHIBAYAMA et al.	Atty Docket No.: MIY-0214 (85318-0214)
Application No.:	Not Yet Assigned	Filing Date: Concurrently Herewith
Title:	THERMOPLASTIC RESIN COMPOSITION, MATERIAL FOR SUBSTRATE AND FILM FOR SUBSTRATE	
Documents Filed:		
Return Receipt Postcard, ISR PCT/IB/304, PCT/IB/306, PCT/IB/308 (supplemental notice)		
English language translation of the International application (58 pages)		
Transmittal Letter to the United States Designated-Elected Office (3 pages)		
First Preliminary Amendment (5 pages)		
Oath or declaration of the inventor(s) (2 pages)		
Drawings (1 sheet; 1 Figure)		
Via:	Courier	Information Disclosure Statement (2 pages)
Sender's Initials:	DTN/LC/tdg	IDS Citations (1 page, 9 references)
Charge \$1440.00 to deposit account 18-0013		
 JUN 14 2006 PATENT & TRADEMARK OFFICE		
Date: June 14, 2006		

JAP15 Rec'd PCT/PTO 14 JUN 2006		
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Application No.:	Not Yet Assigned	Filing Date: Concurrently Herewith
Title:	THERMOPLASTIC RESIN COMPOSITION, MATERIAL FOR SUBSTRATE AND FILM FOR SUBSTRATE	
10/582883		
Documents Filed:		
Return Receipt Postcard, ISR PCT/IB/304, PCT/IB/306, PCT/IB/308 (supplemental notice)		
English language translation of the International application (58 pages)		
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Objection to the Specification

The specification is objected to for the informalities set forth in items 1-6 of the Office Action. Applicant has amended the specification to address each concern raised by the Examiner. Thus, in view of the amendments to the specification, withdrawal of this objection is respectfully requested.

Objection to the Claims

Claims 6, 8 and 11-16 are objected to for the informalities set forth in items 7-9 of the Office Action. Applicant believes that the above amendments to the claims overcome the outstanding objection by addressing each concern raised by the Examiner. Thus, in view of such amendments to the claims, withdrawal of the outstanding objection is respectfully requested.

Rejections under 35 U.S.C. §102

Claims 1-16 are rejected under 35 U.S.C. §102(b) as allegedly being anticipated by Li et al. (U.S. Patent No. 6,060,549), Yonezawa et al. (WO 02/046312, later filed as EP 1 350 815 A1 and U.S. Patent Application Publication No. 2004-0053061), Fukatani et al. (WO 01/036532, later filed as U.S. Patent No. 6,924,334 and EP 1 245 632 A1) (with support from Yonezawa et al.) and Iwade et al. (WO 2002/ 016479, later filed as U.S. Patent Application Publication No. 2005-020404). Further, claims 1-16 are rejected under 35 U.S.C. §102(f) for allegedly lacking inventorship. Applicant believes that the above amendments to the claims overcome the outstanding rejections since the claims are now directed to a process for a molded article which is shaped by molding.

An important feature of the present invention is that the shape by transfer of the shape of the die is highly maintained at high temperatures, particularly not less than 70% of the shape provided by transfer before curing being maintained at temperatures above the glass transition point of said thermoplastic resin. This important feature is obtained due to the specific thermoplastic resin composition defined in claim 1 which enables the shape before curing to be highly maintained at temperatures above the glass transition point of said thermoplastic resin.

Based on Applicant's review of Li et al., Yonezawa et al., Fukatani et al. and Iwade et al., all of the cited references do not teach or suggest such feature of the present invention (i.e. excellent shape retainability at high temperatures). Hence, for this reason, Applicant believes that one skilled in the art cannot readily arrive at the present invention based on the teachings and suggestions of Li et al., Yonezawa et al., Fukatani et al. and Iwade et al.

Thus, withdrawal of the present rejections is respectfully requested.

CONCLUSION

For the foregoing reasons, all the claims now pending in the present application are believed to be clearly patentable over the outstanding rejections. Accordingly, favorable reconsideration of the claims in light of the above remarks is courteously solicited. If the Examiner has any comments or suggestions that could place this application in even better form, the Examiner is requested to telephone the undersigned attorney at the below-listed number.

Dated: December 9, 2008

Respectfully submitted,

By: _____

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Should additional fees be necessary in connection with the filing of this paper, or if a petition for extension of time is required for timely acceptance of same, the Commissioner is hereby authorized to charge Deposit Account No. 50-4422 for any such fees; and applicant(s) hereby petition for any needed extension of time.